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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Roy MATHIEU  
Serial No.: 09/420,478  
Conf. No.: 2856  
Filed: October 19, 1999  
For: POWER COMPONENT BEARING INTERCONNECTIONS  
Examiner: Nathan W. Ha  
Art Unit: 2814

11/17/Arnold B  
Arnold  
1/30/03

**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

The undersigned hereby certifies that this document is being placed in the United States mail with first-class postage attached, addressed to Commissioner for Patents, Washington, D.C. 20231, on January 14, 2003.

*Eileen Casey*  
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Commissioner for Patents  
Washington, D.C. 20231

Sir:

**AMENDMENT**

In response to the Office Action mailed August 14, 2002, please amend the above-identified application as follows:

**IN THE CLAIMS**

Please add new claim 4 as shown below:

4. (New) A high voltage device formed in a region of a silicon substrate of a first conductivity type delimited by a wall of a second conductivity type, comprising:  
a lower surface comprising a first region of the second conductivity type connected to the wall;  
an upper surface comprising a second region of the second conductivity type;